

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
LAKSHMI KANTA BERA	12/15/2014
SURANI BIN DOLMANAN	12/15/2014
MANIPPADY KRISHNA KUMAR	12/15/2014
RASANAYAGAM SIVASAYA KAJEN	12/15/2014
SUDHIRANJAN TRIPATHY	12/15/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	AGENCY FOR SCIENCE, TECHNOLOGY AND RESEARCH
<b>Street Address:</b>	1 FUSIONOPOLIS WAY, #20-10 CONNEXIS
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<b>Postal Code:</b>	138632
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15029835
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(617)502-5000
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<b>ATTORNEY DOCKET NUMBER:</b>	2008187-0076
<b>NAME OF SUBMITTER:</b>	JOHN C. CAHILL
<b>SIGNATURE:</b>	/John J. Cahill/
<b>DATE SIGNED:</b>	04/15/2016
<b>Total Attachments: 4</b>	
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**DEED OF ASSIGNMENT**

**THIS DEED** made the 15 day of December two thousand and fourteen (2014)  
**BETWEEN,**

**BERA, Lakshmi Kanta**

c/o Institute of Materials Research & Engineering,  
 3 Research Link, Singapore 117602

**DOLMANAN, Surani Bin**

c/o Institute of Materials Research & Engineering,  
 3 Research Link, Singapore 117602

**KUMAR, Manippady Krishna**

c/o Institute of Materials Research & Engineering,  
 3 Research Link, Singapore 117602

**KAJEN, Rasanayagam Sivasaya**

c/o Institute of Materials Research & Engineering,  
 3 Research Link, Singapore 117602

**TRIPATHY, Sudhiranjan**

c/o Institute of Materials Research & Engineering,  
 3 Research Link, Singapore 117602

[hereinafter referred to as "the Assignors"]

**AND**

**Agency for Science, Technology and Research**

1 Fusionopolis Way, #20-10 Connexis,  
 Singapore 138632

[hereinafter referred to as "the Assignee"]

**WHEREAS** the Assignor warrants that the Assignor is the true inventor of an invention with the title "**Semiconductor Device Fabrication**" [hereinafter referred to as "the Invention"] the subject of International Patent Application No. **PCT/SG2014/000495**, including the designation of the United States of America [hereinafter referred to as "the Application"]

AND WHEREAS the Assignors have agreed to assign to the Assignee and the Assignee desire to take assignment of all rights, title and interest of the Assignors in and to the Invention and the Application,

NOW THIS DEED WITNESSETH

1. In consideration of the sum of one dollar (\$1) and other good and valuable consideration receipt of which is hereby acknowledged by the Assignors, the Assignors hereby assign to the Assignee all of their rights, title and interest in and to the Invention and the Application including:

- (a) all rights and powers to make one or more applications for Letters Patent or other form of protection in the name of the Assignee in Singapore, the United States of America and in any other country of the world in respect of the Invention, and all rights, title and interest in and to any Letters Patent or other form of protection to mature from any such application,
- (b) the rights and powers to prosecute the Application and all rights, title and interest in and to any Patent or Patents granted thereon together with any extension of the term of any such Patent or Patents as may be granted, SAVE THAT nothing in this Deed shall prevent the filing or proceeding of an Application to which this Deed relates, in the name of the Assignors or Inventors where such filing or proceeding of such Application is beneficial to the interests of the Assignee,
- (c) the rights and powers to seek protection in countries other than Singapore by way of Patent, Petty Patent, Utility Model, Design Patent or other appropriate form of protection for the Invention, by way of application(s) for such protection made to the appropriate authorities in such other country or countries as the Assignee in its complete discretion may elect, whether or not any such foreign application(s) be made claiming International Convention priority from the Application hereby assigned,
- (d) any Copyright owned by the Assignors in and to any drawings relating to the subject matter of the Invention together with the rights and powers such as subsist at the date of this Deed,
- (e) to apply for registration of Copyright, Design, Design-Patent or like protection in the name of the Assignee in Singapore and in any other country of the world in respect of the subject matter of the said drawings and to any registration of Copyright, Design-Patent or like protection which matures from any such application, together with the rights to sue in respect of any infringement of that Copyright which may have occurred before the date of this Deed,

2. The Assignors agree, at the expense of the Assignee, to sign, execute and deliver all documents, forms and papers reasonably required to be produced or obtained by the Assignee in connection with any application for Letters Patent or other form of protection for the subject matter of the invention, in Singapore or elsewhere.

IN WITNESS WHEREOF the Assignors and Assignee executed this Deed the day and year first hereinbefore written.

**ASSIGNORS**

SIGNED, SEALED and DELIVERED

By the said **BERA, Lakshmi Kanta**

*Lakshmi Kanta Bera*  
15/12/2014

in the presence of:

*Kelin Keler*  
.....  
(Witness) 15/12/2014

SIGNED, SEALED and DELIVERED

By the said **DOLMANAN, Surani Bin**

*[Signature]*  
.....  
15/12/14

in the presence of:

*WY - WONG TEN IT*  
.....  
(Witness) 15/12/2014

SIGNED, SEALED and DELIVERED

By the said **KUMAR, Manippady Krishna**

*M. Krishnakumar*  
.....  
12/12/2014

in the presence of:

*Ajay Kushwah*  
.....  
(Witness) 12/12/2014

SIGNED, SEALED and DELIVERED

By the said **KAJEN, Rasanayagam Sivasaya**

*Kajen*, 15-12-2014

in the presence of:

*Kedari*  
*Hippalgaonkar*  
 15-12-2014  
 (Witness)

SIGNED, SEALED and DELIVERED

By the said **TRIPATHY, Sudhiranjan**

*Sudhiranjan Tripathy*, 15-12-2014

in the presence of:

*Kedari*  
*Hippalgaonkar*  
 15-12-2014  
 (Witness)

**ASSIGNEE**

FOR AND ON BEHALF OF

By the said

**Agency for Science, Technology and Research**

in the presence of:

*Kohwiler*  
 (Witness) CECILIA KOH

*[Signature]*  
**SURESAN SACHI**  
 GENERAL COUNSEL  
 AGENCY FOR SCIENCE, TECHNOLOGY AND RESEARCH